IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A plasma processing system comprising:

a process chamber;

an upper electrode assembly;

a fluid flow control member including a plurality of recesses; and

a chuck assembly including a plurality of lift pin assemblies, for lifting the fluid flow control member at at least one location, each lift pin assembly including a lift pin configured to engage with a respective recess of the fluid flow control member to directly lift the fluid flow control member.

Claim 2 (Original): The plasma processing system of claim 1 wherein the chuck assembly comprises at least one of an RF electrode and an electrostatic clamping electrode.

Claim 3 (Original): The plasma processing system of claim 1 wherein the fluid flow control member comprises a focus ring.

Claim 4 (Withdrawn): The plasma processing system of claim 1 wherein the fluid flow control member comprises a pumping baffle.

Claim 5 (Withdrawn): The plasma processing system of claim 1 wherein the fluid flow control member comprises an auxiliary focus ring.

Claim 6 (Original): The plasma processing system of claim 1 wherein lift pins of each of the plurality of lift pin assemblies are lifted simultaneously.

Claim 7 (Original): The plasma processing system of claim 1 wherein lift pins of each of the plurality of lift pin assemblies are controllable to be lifted individually.

Claim 8 (Canceled).

Claim 9 (Original): The plasma processing system of claim 1, further comprising a vacuum port located next to at least one of the plurality of lift pin assemblies.

Claim 10 (Original): In a movable focus ring the improvement comprising:

a hole for facilitating lifting of the focus ring by lift pins.

Claim 11 (Original): In a movable focus ring the improvement comprising:

a recess for facilitating lifting of the focus ring by lift pins.

Claim 12 (New): The plasma processing system of claim 1, wherein the lift pin extends through a horizontal surface of the chuck assembly when the lift pin is fully retracted.

Claim 13 (New): The plasma processing system of claim 12, wherein the lift pin engages the respective recesses of the fluid flow control member when the lift pin is fully retracted.

Claim 14 (New): A plasma processing system comprising:

a process chamber;

an upper electrode assembly;

a fluid flow control member including a plurality of recesses; and

a chuck assembly including a plurality of lifting means for lifting the fluid flow control member at at least one location, each lifting means engaging a respective recess of the fluid flow control member to directly lift the fluid flow control member.

Claim 15 (New): The plasma processing system of claim 14, wherein the lifting means extends through a horizontal surface of the chuck assembly when the lifting means is fully retracted.

Claim 16 (New): The plasma processing system of claim 15, wherein the lifting means engages the respective recesses of the fluid flow control member when the lifting means is fully retracted.

Claim 17 (New): The plasma processing system of claim 14 wherein the fluid flow control member comprises a focus ring.

Claim 18 (New): The plasma processing system of claim 14 wherein the fluid flow control member comprises a pumping baffle.

Claim 19 (New): The plasma processing system of claim 14 wherein the fluid flow control member comprises an auxiliary focus ring.

Claim 20 (New): The plasma processing system of claim 14 wherein the plurality of lifting means are lifted simultaneously.

Claim 21 (New): The plasma processing system of claim 14 wherein the plurality of lifting means are controllable to be lifted individually.